

1. Product Description:

1. L/W/H: 2.1 x 0.6 x 1.0 mm

2. Color: High brightness Yellow

3. Colloid: Transparency colloid

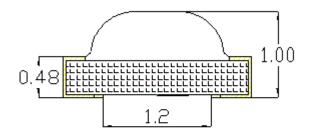
4. EIA Standard Packaging

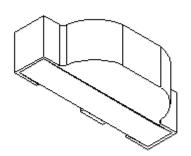
5. Eco-friendly products, ROHS compliant

6. For automatic pitchers

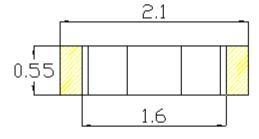
For reflow welding processes

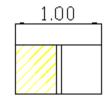
2. Form factor and recommended pad size:



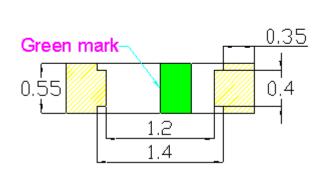


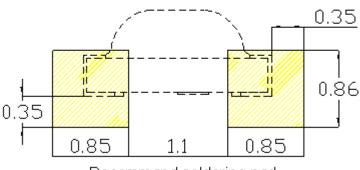
MODEL: 2106UYC-S











Recommand soldering pad

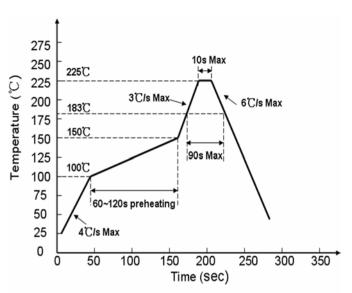
Note:

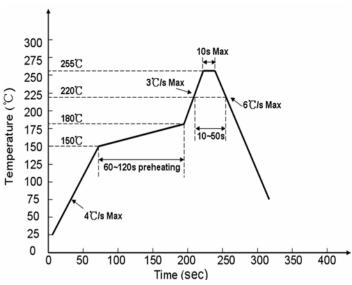
1. Units: mm (mm)

2. Tolerance: .10 mm without special labels



3. The recommended welding temperature curve:





FFor Lead SolderSolder

For Lead Free Solder

4. Maximum absolute rating Ta=25℃

Number of parameters	The no.	Maximum rating	Single-bit
power dissipation	Pd	55	mW
Maximum pulse current (1/10 duty ratio, 0.1ms pulse width)	Ifp	100	mA
Forward DC operating current	IF	25	mA
Reverse voltage	V_R	5	${f V}$
Working environment temperature	Topr	-30°C~+ 85°C	
Storage ambient temperature	Tstg	-40°C~+ 90°C	
Welding conditions	Tsol	Reflow welding: 260°C, 10s Manual welding: 300°C,3s	



$5.\ \textbf{Photoelectric parameters}$

(Ta=25℃):

MODEL: 2106UYC-S

Parameters	Symbol	Min.	Typical	Max.	Unit	Test conditions
Luminous intensity	IV		45		mcd	IF=5mA
viewing angle	2θ1/2		120		deg	IF=5mA
Forward voltage	VF	1.6		2.2	V	IF=5mA
Reverse current	IR			5	uA	VR=5V
Wavelength	λD		588		nm	IF=5mA

Brightness split:

Code	Min.	Max.	Unit	Test conditions
J3	20	25		
J4	25	30		
K3	30	37	1	IF 5 A
K4	37	44	mcd	IF=5mA
L3	44	53		
L4	53	64		

Note:Luminous intensity ± 11%

Woltage split

Code	Min.	Max.	Unit	Test conditions
2A	1.6	1.7		
2B	1.7	1.8		
3A	1.8	1.9	V	IF=5mA
3B	2.0	2.1		
4A	2.1	2.2		

wavelength split:

Code	Min.	Max.	Unit	Test conditions
А	582.5	585		
В	585	587.5		IE 5m A
С	587.5	590	nm	IF=5mA
D	590	592.5		
E	592.5	595		

Note: Wavelength tolerance±1nm

Forward voltage tolerance $\pm 0.02V$



6. Photonic parameters represent value characteristic curves:

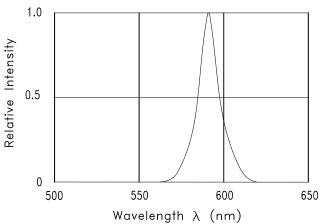


Fig.1 RELATIVE INTENSITY VS. WAVELENGTH

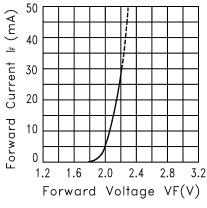


Fig.2 FORWARD CURRENT VS.
FORWARD VOLTAGE

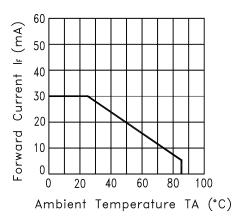


Fig.3 FORWARD CURRENT DERATING CURVE

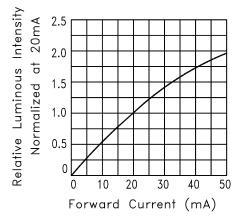


Fig.4 RELATIVE LUMINOUS
INTENSITY VS. FORWARD CURRENT

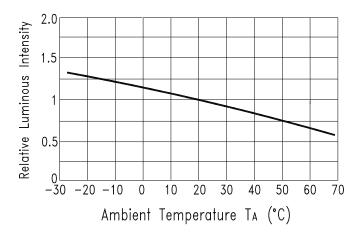
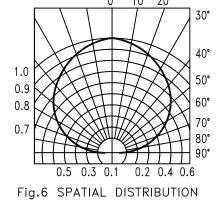


Fig.5 Luminous Intensity vs.Ambient Temperature



Note: If not otherwise noted, the test ambient temperature is $25 + 3^{\circ}$ C

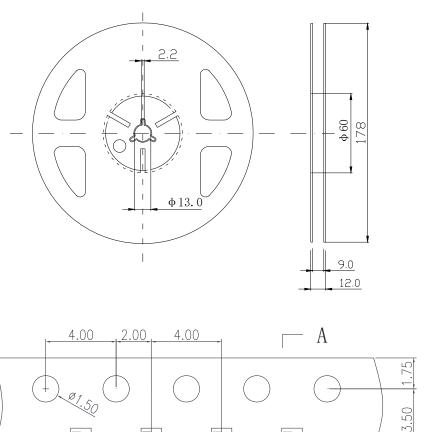


7. Labels and logos:

P/N: Product Name WLD: Wavelength QTY: Product quantity

LOT No.:Production Lot Code

8. Packed carrier and disc size:



Note: 1. Unit: mm

2. Tolerance: -0. 15 mm without a special label

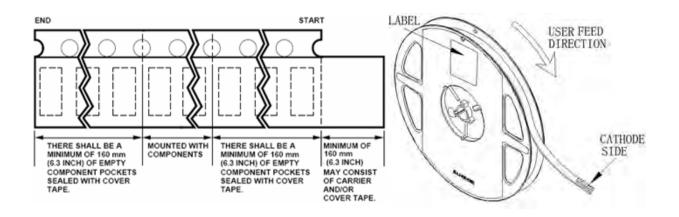
UserFeed Direction

A

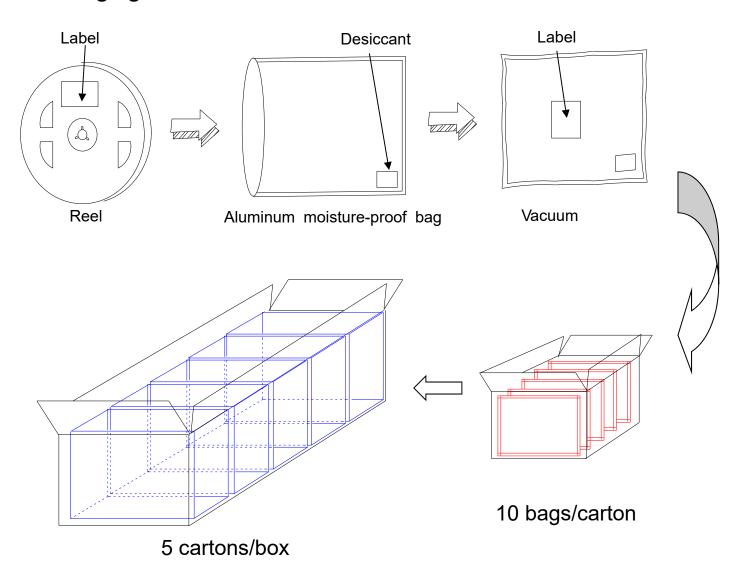
A-A剖面图



9. Tape Leader & Trailer Dimensions And Reel



10. Packaging:





11. Reliability Test MODEL: 2106UYC-S

Appendix	Classification	Test Item	Test Condition	Reference Standard	Reference Standard
Endurance Test High Humidity Storage Ta= 65±5 C, RH= 90 ~ 95% 240HRS±2HRS JIS C 7021:B-11		Operation Life	·		MIL-STD-750D:1026 MIL-STD-883D:1005 JIS C 7021:B-1
Ta= 105±5°C				240HRS±2HRS	MIL-STD-202F:103B JIS C 7021:B-11
Ta=-5st5C Temperature T	Endurance Test		Ta= 105±5°C		MIL-STD-883D:1008 JIS C 7021:B-10
Interpretative		-	Ta=-55±5°C		JIS C 7021:B-12
Thermal Shock 85 ± 5°C ~ -40°C ± 5°C 10 mins		-			MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1010 JIS C 7021:A-4
Solder Resistance T.sol= 240 ± 5 C Total two times MIL.STD.750D.203 JIS C 7021.A-1 MIL.STD.750D.203 JIS C 7021.A-1 MIL.STD.750D.2031.2 MIL.STD.750D.2031.2 MIL.STD.750D.2031.2 J-STD-020C MIL.STD.750D.2031.2 MIL.STD.750D.2031.2 J-STD-020C MIL.STD.750D.2031.2 J-STD-020C MIL.STD.750D.2031.2 Immersion time 2±0.5 sec MIL.STD.750D.2031.2 MIL-STD.750D.2031.3 J-STD-020C MIL.STD.750D.2031.3 J-STD-020C MIL.STD.750D.2031.3 MIL-STD-020C MIL.STD.750D.2031.3 MIL-STD-750D.2031.3 J-STD-020C MIL.STD.750D.2031.3 MIL-STD-750D.2031.3 J-STD-020C MIL-STD-750D.2031.3 MIL-STD-750D.2031.3 J-STD-020C MIL-STD-750D.2031.3 MIL-STD-750D.2031.3		Thermal Shock	85 ± 5°C ∼ -40°C ± 5°C	10 Cycles	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1011
IR-Reflow Normal Process IR-Reflow Normal Process IR-Reflow Pb Free Process Solderability IR-Reflow Pocess IR-Reflow Pb Free Process Solderability IR-Reflow Pocess IR-Reflow Pocess IR-Reflow Pb Free Process IR-Reflow Pb Free Process Solderability IR-Reflow Pocess IR-Reflow Pb Free Process IR-Reflow Pb Free Process Pocess P		Solder Resistance	T.sol= 240 ± 5℃		MIL-STD-202F:210A MIL-STD-750D:2031 JIS C 7021:A-1
IR-Reflow Pb Free Process Temp. maintain at 175(±25)°C 180 seconds max Temp. maintain above 217°C 60-150 seconds Peak temperature range 260°C+0/-5°C Time within 5°C of actual Peak Temperature (tp) 20-40 seconds Ramp-down rate +6°C/second max T.sol= 235 ± 5°C Immersion rate 25±2.5 mm/sec Coverage ≥95% of the dipped surface Immersion time 2±0.5 sec MIL-STD-202F:208 MIL-STD-202F:208 MIL-STD-750D:202 MIL-STD-750D:202 Immersion time 2±0.5 sec Immersion time 2±0.5 sec			max Temp. maintain at 125(±25)°C 120 seconds max Temp. maintain above 183°C 60-150 seconds Peak temperature range 235°C +5/-0°C Time within 5°C of actual Peak Temperature (tp) 10-30 seconds		STD-750D:2031.2
Solderability Immersion rate 25±2.5 mm/sec Immersion time 2±0.5 sec MIL-STD-750D:202 MIL-STD-883D:200 IEC 68 Part 2-20			max Temp. maintain at 175(±25)°C 180 seconds max Temp. maintain above 217°C 60-150 seconds Peak temperature range 260°C+0/-5°C Time within 5°C of actual Peak Temperature (tp) 20-40 seconds		STD-750D:2031.2
		Solderability	Immersion rate 25±2.5 mm/sec	Immersion time 2±0.5 sec	



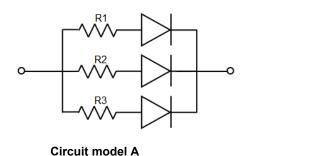
12. Cautions Application

1. A LED is a current-operated device. The slight shift of voltage will cause big change of current, which will damage LEDs.

Customer should use resistors in series for the Over-Current-Proof.

 In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended to use individual resistor separately, as shown in Circuit A below. The brightness of each LED shown in Circuit B might appear difference due to the differences in the

I-V characteristics of those LEDs.



Circuit model B

- 3. High temperature may reduce LEDs' intensity and other performances, so keeping it away from heat source to get good performance is necessary.
- 4. Photonic parameter tolerance:

Forward voltage REF/VF: ±0.1V

Brightness CAT/IV: ±15%
Wavelength HUE/WLD: ±nm

Storage

1.Before opening original package, it is recommended to store them in the following environment:

Temperature: 5°C~30°C Humidity: 85%RH max.

- 2. After opening original package, the storage ambient for the LEDs should be in 5~30°C temperature and 60% or less relative humidity.
- 3. In order to avoid moisture absorption, it is recommended that the LEDs that out of the original package should be stored in a sealed container with appropriate desiccant, or in desiccators with nitrogen ambient.
- 4. The LEDs should be used within 168hrs (7 days) after opening the package. Once been mounted, soldering should be quick.
- 5. If the moisture absorbent material (silica gel) has faded away or the LEDs stored out of original package for more than 168hrs (7 days), baking treatment should be performed using the conditions: 60°C at least 24 hours.



ESD (Electrostatic Discharge)-Protection

A LED (especially the Blue. White and Green product) is an ESD sensitive component, and static electricity or power surge will damage the LED. ESD-damaged LEDs will exhibit abnormal characteristics such as high reverse leakage current, low forward voltage, or "no light-up" at low currents, etc.

Some advice as below should be noticed:

- 1. A conductive wrist strap or anti-electrostatic glove should be worn when handling these LEDs.
- 2. All devices, equipment, machinery, work tables and storage racks, etc. must be properly

grounded.

- 3. Use anti-static package or boxes to carry and storage LEDs. And ordinary plastic package or boxes is forbidden to use.
- 4. Use ionizer to neutralize the static charge during handling or operating.
- 5. All surfaces and objects within 1 ft close to LEDs measure less than 100V.

Cleaning

Use alcohol-based cleaning solvents such as IPA (isopropyl alcohol) to clean LEDs if necessary.

Soldering

- 1. Soldering condition refer to the draft "Soldering Profile Suggested" on page 1.
- 2. Reflow soldering should not be done more than 2 times.
- 3. Manual soldering is only suggested on repair and rework. The maximum soldering temperature should not exceed 300°C within 3 sec. And the maximum capacity of soldering iron is 30W in power.
- 4. During the soldering process, do not touch the lens at high temperature.
- 5. After soldering, any mechanical force on the lens or any excessive vibration shall not be accepted to apply, also the circuit board shall not be bent as well.

Others

- 1. The LEDs described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household applications). Consult Gtlight's Sales in advance for the applications in which exceptional reliability is required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health. (such as in aviation, transportation, traffic control equipment, medical and life support systems and safety devices).
- 2. The light output from the high luminous intensity LEDs may cause injury to human eyes when viewed directly.
- 3. The appearance and specifications of the product may be modified for improvement without prior notice.